

Title (en)

Method for the electrolytic deposition of copper

Title (de)

Verfahren zur elektrolytischen Abscheidung von Kupfer

Title (fr)

Procédé pour la déposition électrolytique de cuivre

Publication

EP 1630258 A1 20060301 (DE)

Application

EP 05018241 A 20050823

Priority

DE 102004041701 A 20040828

Abstract (en)

The flow rate of the electrolyte of the matting process is significantly increased by treating with an electrolyte containing copper in an acid (Copper alkydsulphate).

IPC 8 full level

C25D 3/38 (2006.01)

CPC (source: EP US)

C25D 3/38 (2013.01 - EP US)

Citation (search report)

- [XA] EP 1408141 A1 20040414 - ENTHONE [US]
- [XA] US 6676823 B1 20040113 - BOKISA GEORGE [US]
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- [A] US 4036711 A 19770719 - KARDOS OTTO, et al
- [A] US 4134803 A 19790116 - ECKLES WILLIAM E, et al

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